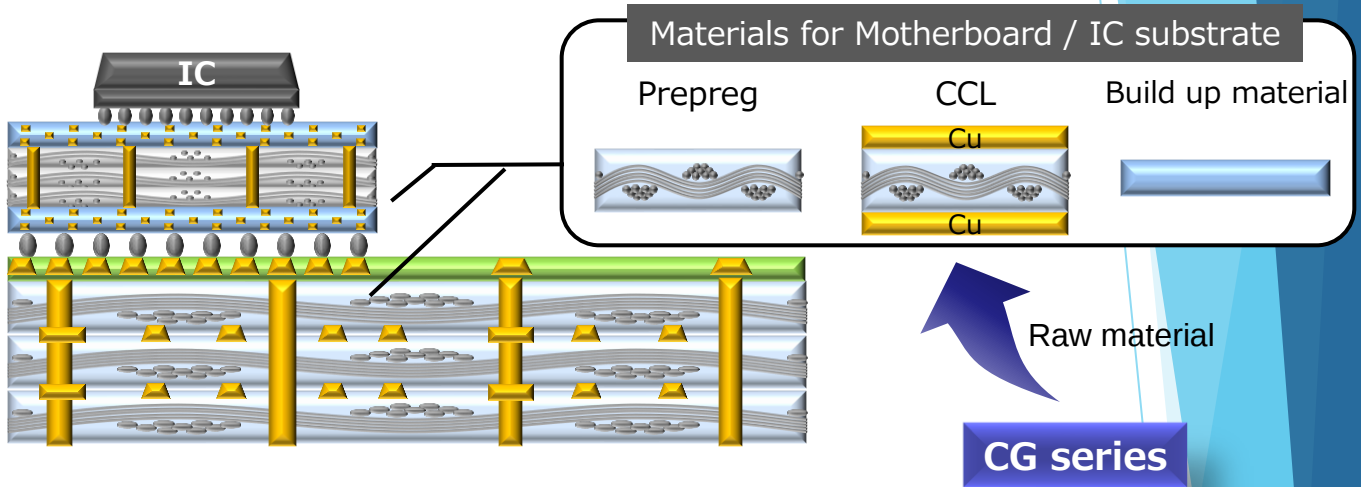


CG-7000 series

Low Df materials for PCB

Application



Properties

		CG-7011	CG-7012	CG-7013
Feature		Ultra low Df High Tg Good adhesion	Ultra low Df Excellent adhesion	Ultra low Df Excellent adhesion
Curing system		Radical-curable	Radical-curable	Radical-curable
Product	Non-volatile (%)	58	58	40
	Solvent	Toluene	Toluene	Toluene
Properties	Dk/Df @10GHz	2.6/0.0008	2.6/0.0009	2.6/0.0009
	Tg (°C, DMA)	220	170	160
Composition Initiator 0.5phr	Peel strength (N/mm, with low profile Cu)	0.5	0.8	1.3

Curing Condition: 200°C x 2h, under N₂.